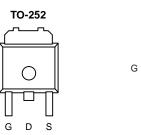
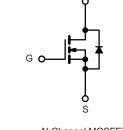


## N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
60	0.010 at V <sub>GS</sub> = 10 V	60		
50	0.011 at V <sub>GS</sub> = 4.5 V	58		





#### N-Channel MOSFET

D

## FEATURES

- 175 °C Junction Temperature
- TrenchFET<sup>®</sup> Power MOSFET
- Material categorization:



ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> :	= 25 °C, unless othe	rwise noted)			
Parameter	Symbol	Limit	Unit		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>1</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C		60		
Continuous Drain Current $(1_J = 175 °C)^2$	T <sub>C</sub> = 100 °C	I <sub>D</sub>	48 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	100	А		
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	50 <sup>a</sup>			
Avalanche Current	I <sub>AS</sub>	50			
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ	
Maximum Bawar Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	- w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	R <sub>thJA</sub>	15	18	°C/W	
Maximum Junction-to-Ambient*	Steady State		40	50		
Maximum Junction-to-Case	R <sub>thJC</sub>	0.85	1.1			

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t  $\leq$  10 s.



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	rce Breakdown Voltage $V_{DS}$ $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1	2	3	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μA	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.010			
- ·		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.016		6	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	0.020			Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.011		-	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			4100			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225		1	
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$		15	25		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 50 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		35	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30	1	
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)		·			
Pulsed Current	I <sub>SM</sub>				60	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns	

<b>SPECIFICATIONS</b> (T <sub>1</sub> = 25 °C, unless otherwise noted)	SF	<b>ECIFIC</b>	CATIONS	$(T_1 = 25 \ ^{\circ}C_1)$	unless otherwise noted)
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Notes:

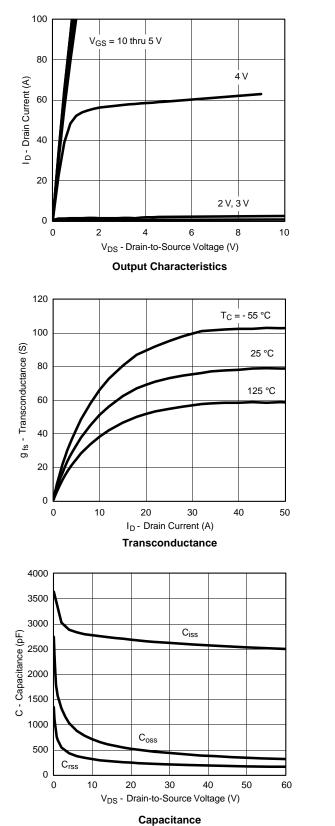
a. For design aid only; not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

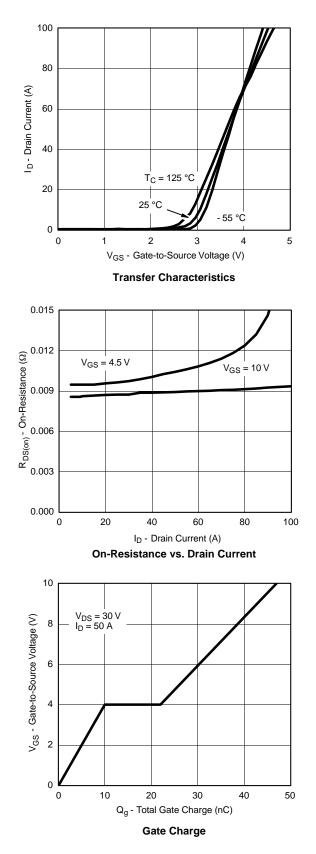
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

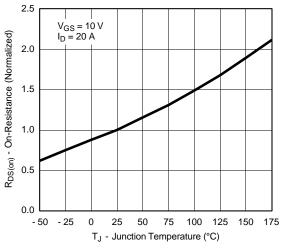




### TYPICAL CHARACTERISTICS (25 °C unless noted)

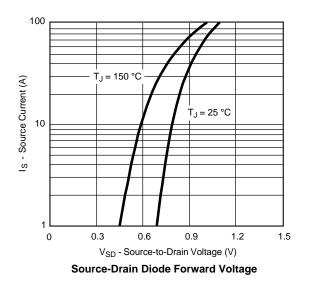






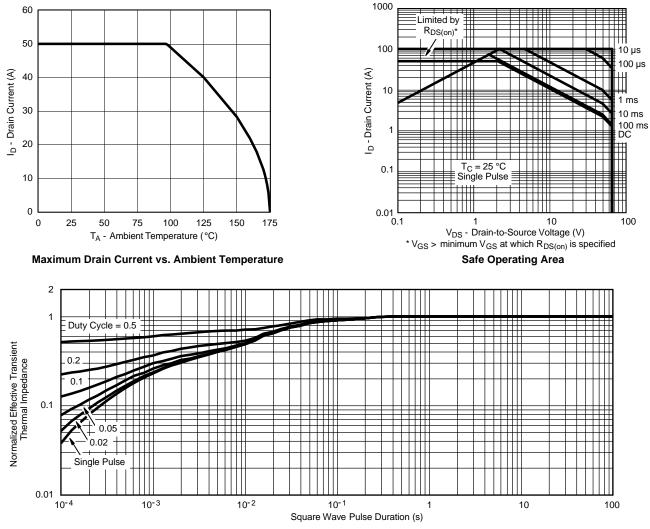
## TYPICAL CHARACTERISTICS (25 °C unless noted)

**On-Resistance vs. Junction Temperature** 





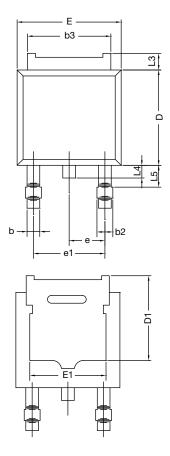
#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



# **TO-252AA CASE OUTLINE**





	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC 0.090 BSC					
e1	4.56	BSC	0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

#### Note

• Dimension L3 is for reference only.



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